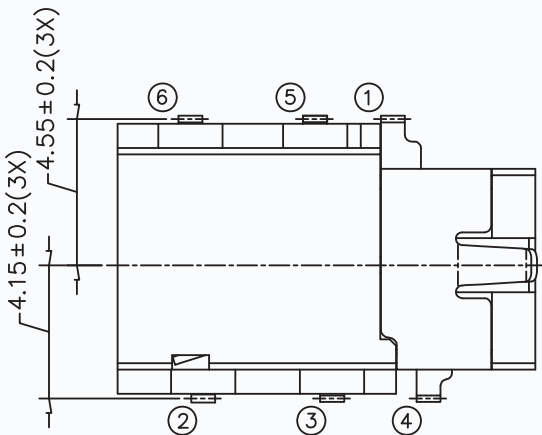
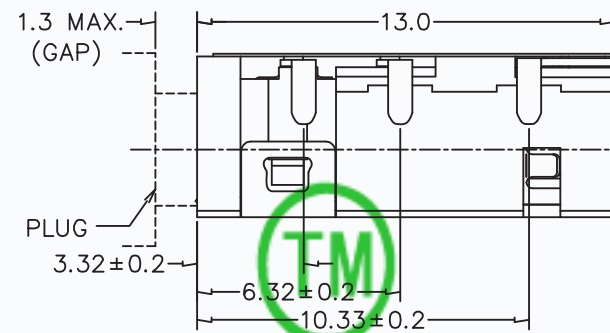
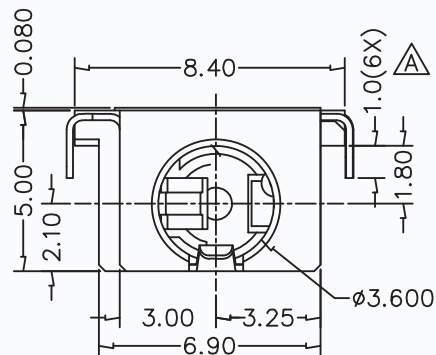
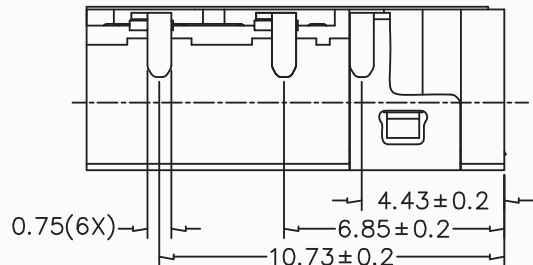
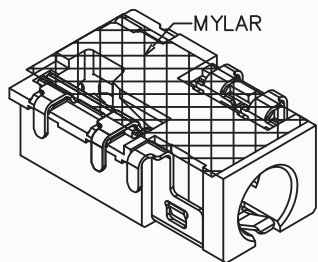


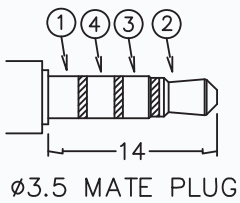
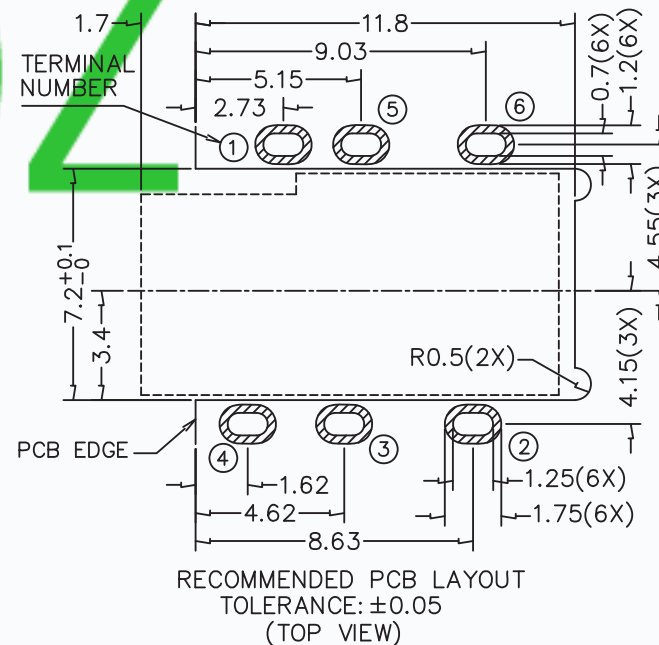
CAD FILE:



CMTDDZ

*** MATERIAL**

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 5 : COPPER ALLOY
- TERMINAL 6 : COPPER ALLOY
- HOUSING : PA10T
- INSULATOR : PA10T
- MYLAR : POLYIMIDE



MODEL NO.	T13-3574D
SCHMATIC	

APPD.	DESCRIPTIONS OF REVISION
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TOLERANCE UNLESS SPECIFIED
WITHIN 1.5mm : ±0.1mm
OVER 1.5mm : ±0.2mm

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TITLE : 3.5mm PHONE JACK
MODEL: T13-3574D
CMTDDZ 东莞市田都电子有限公司 DONGGUAN TIANDU ELECTRONICS CO.,LTD.

UNIT : mm	DRWG NO.: CMTDDZ-T13-3574D-00
SCALE: 3:1	DWN. ERIC 2013-6-17
CHK'D MAIKO 2013-6-17	APPD. Coco 2013-6-17